

L Number	Hits	Search Text	DB	Time stamp
1	1	ID adj marking and wafer and circuit	USPAT; EPO; JPO; DERWENT	2004/09/16 18:52
2	978	identi\$6 and circuit and marking and wafer	USPAT; EPO; JPO; DERWENT	2004/09/16 18:53
3	47143	laser adj beam and plate	USPAT; EPO; JPO; DERWENT	2004/09/16 18:54
4	105	(identi\$6 and circuit and marking and wafer) and (laser adj beam and plate)	USPAT; EPO; JPO; DERWENT	2004/09/16 18:54